Product Document

Published by
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Premstätten, January 18, 2018

Process Change Notification PCN01-2018

Test Location Move and Test Platform Transfer for ENS210-LQFM

Dear Customer,

ams has to move the test from our current subcontracted test facility NXP Semiconductors in Taiwan to our subcontracted test facility AMKOR ASSEMBLY & TEST in Shanghai. The facility change will also require a test platform transfer for the affected product.

Product affected:

ENS210-LQFM

Reason for change:

Site consolidation.

Timing of change:

Completion by April 31, 2018.

Test Sites Details:

From: NXP Semiconductors
10. Chin 5th Road, N.E.P.Z. Kaohsiung 811, Taiwan , R.O.C.

To: AMKOR ASSEMBLY & TEST (Shanghai) Co.,Ltd.
Yinglun Road, Factory:No. 111, 200131 Pudong, Shagnghai, China

Impact on Product:

No impact on the product as there will be no change in terms of form, fit, function, and reliability of the devices.

Transfer Acceptance:

Verification of product will include material to be tested before and after the move as described in our internal spec QTY459 Test Program Release with the exception that no SOTF (sample on the Fly test with QA limits) will be done. A BinFlip and TC report will be also done.

Please be advised that unless we received your written refusal concerning this PCN in writing within 30 days, the PCN shall be deemed accepted.

Best Regards,

Dietmar Gleispach
ams AG
Director Operations Division EAS